

Thermexit-XEI

P/N: 08-0060-0.1

KEY FEATURES

- Electrically insulating
- Non-silicone, non-reactive, non-curing system with no resin-filler separation
- ₹ High thermal stability, with continuous operation up to 135°C
- **■** High thermal conductivity
- Facilitates reworkability of the thermal management system
- **Easy pick and place application without residue/mess**
- Highly compressible to minimize contact resistance without high force



TECHNICAL SPECIFICATIONS

Test	Description	Min	Тур	Max	Units
Thermal Conductivity	ASTM D5470 (at 20 psi)		18		W/m*K
Thermal Resistance vs Pressure [1]	ASTM D5470	0.67 at 140 kPa (20 psi)			K-cm ² /W
Compression-Deflection [2]	Modified ASTM C165 In- House Method	17% at 210 kPa (30 psi)			
Electric Resistance	ASTM D257, volume resistivity	1x10 ¹⁴			Ohm-cm
Dielectric Constant/Dielectric Loss @ 1MHz	ASTM D150/ Thermexit In- House Method	4.73/0.009			
Dielectric Strength (Voltage Breakdown)	ASTM D149	7875			Vac/mm
Operating Temperature		-40		135	°C
Storage Temperature/Shelf Life	In packaging, stored between 10-40°C	12			months
Weight Loss (Thermal Stability)	Per TGA (Thermogravimetric Analysis	<0.2% at 150°C			
Outgassing CVCM (Collected Volatile Condensable Materials)	Per ASTM E595	0.07			Wt%
Outgassing TML (Total Mass Loss)	Per ASTM E595	0.20			Wt%
Hardness	Per ASTM D2240	77		87	Shore 00
Flammability [3]	UL94 Vertical	UL94 V-0			
Length		50		mm	
Width		50		mm	
Thickness		0.5		5	mm
Density (Specific Gravity)	In-house method based on ASTM D792	1.71		g/cm ³	
Color		White			
Adhesive Layer		No			
Notes [1]- Using unit thickness of 0.5mm. Additional data available upon request.		Standard length/width is 50mm x 50mm. Refer to Product Variation Catalog			

- [1]- Using unit thickness of 0.5mm. Additional data available upon request.
- [2]- Using unit thickness of 2.0mm. Additional data available upon request.
- [3]- Using unit thickness of 2.5mm. Additional data available upon request.

Standard length/width is 50mm x 50mm. Refer to Product Variation Catalog for complete list sizing

These materials are not deemed by Nanoramic Laboratories to require an SDS. $\label{eq:continuous} % \begin{center} \end{center} \begin{cent$

Disclaimer

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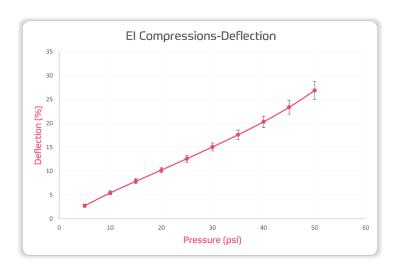
Thermexit-XEI

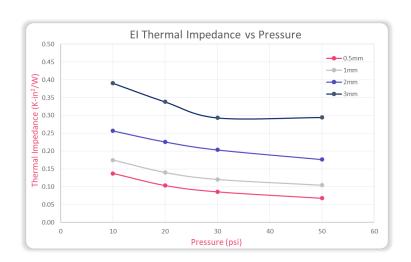
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TYPICAL APPLICATIONS

- Consumer electronics
- Power supplies
- Automotive electronics
- **■** LEDs and Lasers

- **■** Motor controls
- High power semiconductors
- **■** 5G Telecom Infrastructure
- Batteries or energy storage devices





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Rev Number	30		
Last Updated	05/16/2022		